

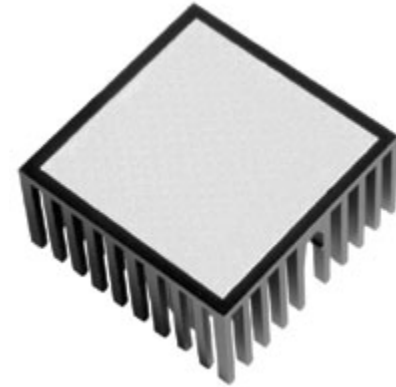


BOARD LEVEL COOLING – 3740

3740 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative Image Only.

ORDERING INFORMATION

| Part Number | Device Type |
|---------------|-------------|
| 374024B00035G | BGA, FPGA |



HEAT SINK DETAILS

| Property | Details |
|----------------------------|-----------------------------|
| Material | Aluminum |
| Finish | Black Anodize |
| Device Attachment Options | Tape |
| Thermal Interface Material | T411 Chomerics Tape for All |

| Property | Details |
|------------------------------|----------------------|
| Heat Sink Width (mm) | 23.00 |
| Heat Sink Length (mm) | 23.00 |
| Heat Sink Height (mm) | 10.00 |
| Heat Sink Mounting Direction | Horizontal, Vertical |

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

